

HZU6.8Z

Silicon Epitaxial Planar Zener Diode for Surge Absorb

REJ03G1219-0200

(Previous: ADE-208-777A)

Rev.2.00 Jun 16, 2005

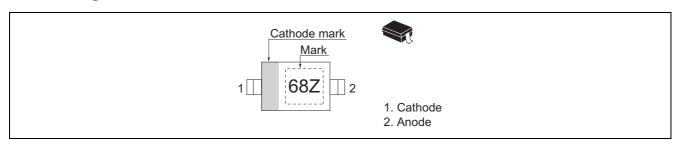
Features

- Low capacitance (C = 25 pF max) and can protect signal line from ESD.
- Ultra small Resin Package (URP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Name	Package Code (Previous Code)
HZU6.8Z	68Z	URP	PTSP0002ZA-A (URP)

Pin Arrangement



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Power dissipation	Pd *	200	mW
Junction temperature	Tj	150	°C
Storage temperature	Tstg	−55 to +150	°C

Note: See Fig.2.

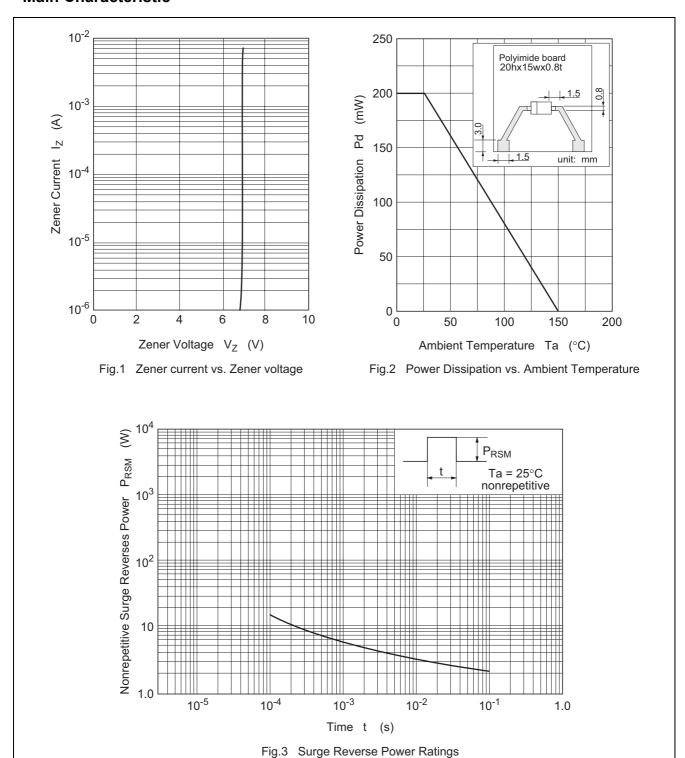
Electrical Characteristics

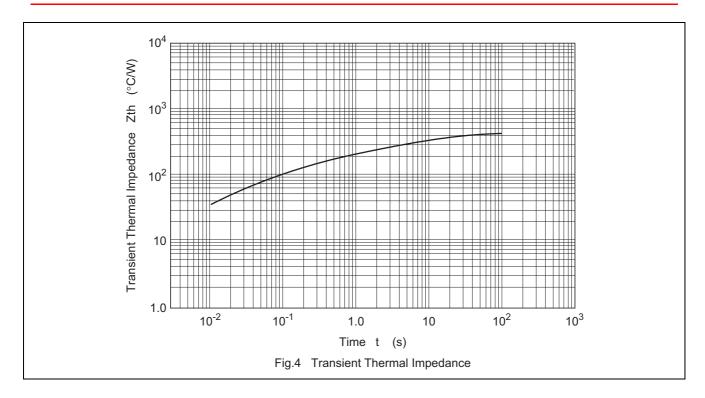
 $(Ta = 25^{\circ}C)$

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Zener voltage	Vz	6.47	_	7.0	V	I_Z = 5 mA, 40 ms pulse
Reverse current	I _R	_	_	2	μΑ	V _R = 3.5 V
Capacitance	С	_	_	25	pF	V _R = 0 V, f = 1 MHz
Dynamic resistance	r _d	_	_	30	Ω	I _Z = 5 mA
ESD-Capability *	_	20	_	_	kV	C = 150 pF, R = 330 Ω , Both forward and reverse direction 10 pulse

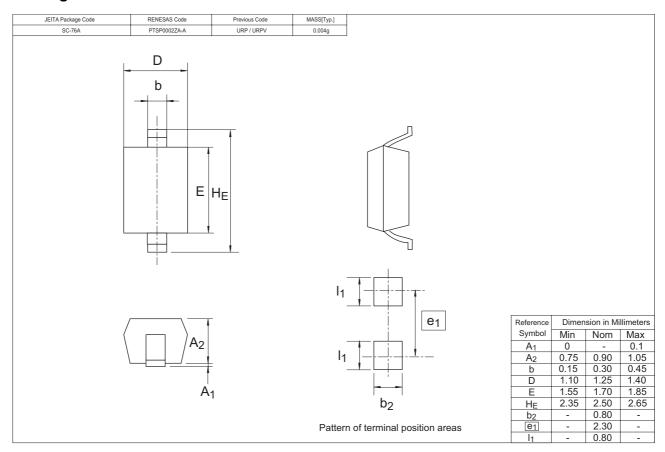
Note: Failure criterion ; $I_R > 2 \mu A$ at $V_R = 3.5 V$.

Main Characteristic





Package Dimensions



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